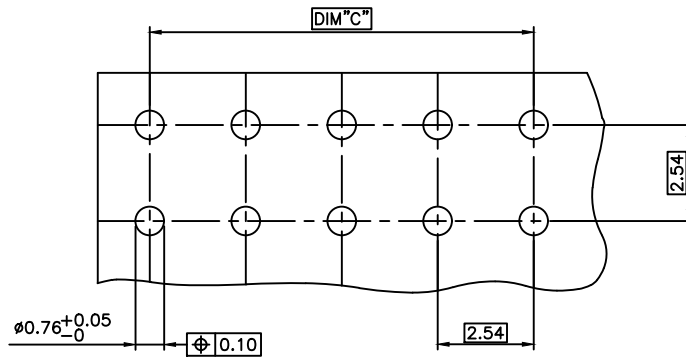
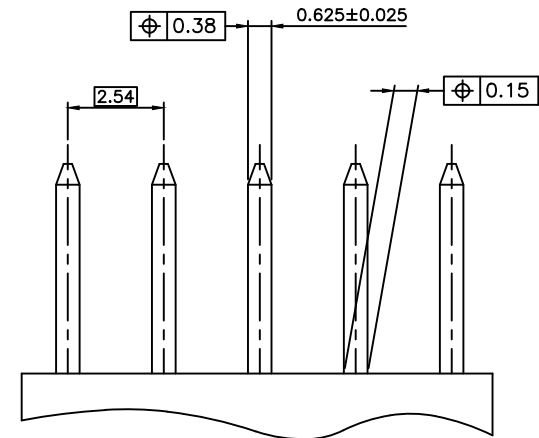


PRODUCT N°	DIM"C"	DIM"D"
91625-YXXLF	SEE TABLE SHEET 2/2	

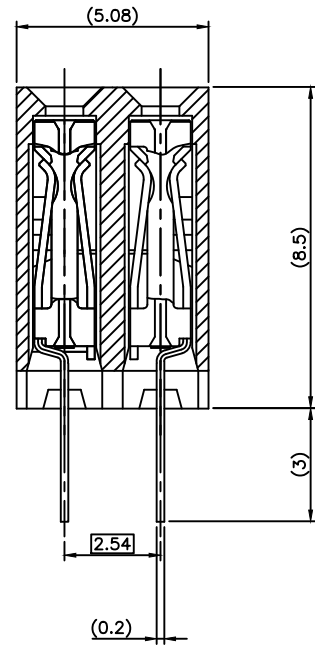
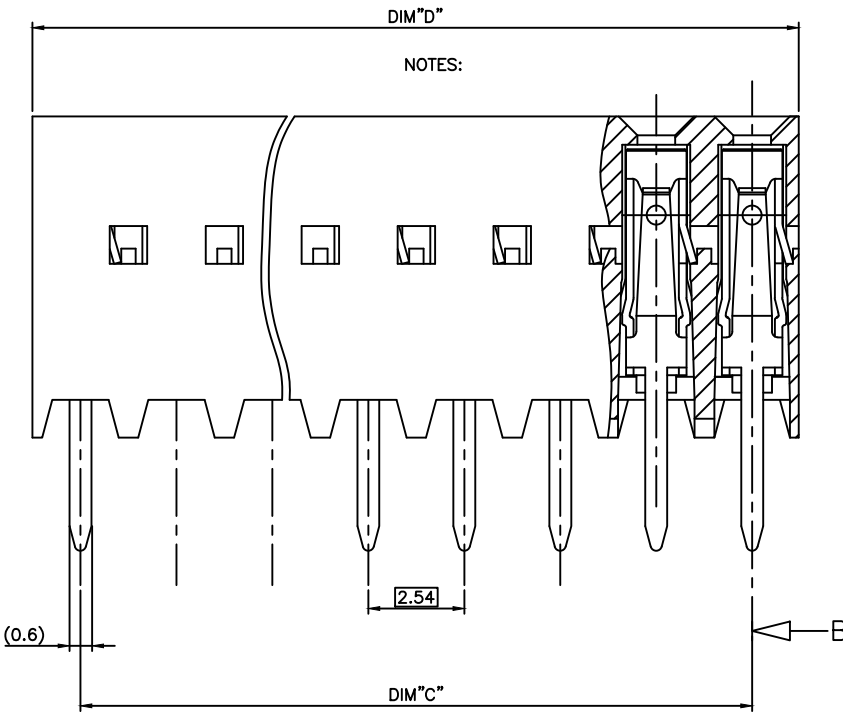
RoHS COMPATIBLE, SEE NOTE 4



RECOMMENDED PC BOARD THICKNESS 1.6 mm MAX.



MINIMUM MATING PIN LENGTH: 5 mm.



SECTION B-B

NOTES:

- 1 - MATERIAL HOUSING: THERMOPLASTIC POLYESTER 30% GLASS FILLED, COLOUR BLUE. FLAME RETARDANT PER UL-94 CATEGORY V0.
- 2 - MATERIAL TERMINAL: PHOSPHOR BRONZE EXTRA HARD.
- 3 - CONNECTOR MEANT TO BE USED FOR PC BOARD WITH NONE PLATED THROUGH HOLES.
- 4 - RoHS COMPATIBLE PRODUCT SPECIFICATIONS
 - a - PLATING:
 - "LF" MEANS THE PRODUCT IS LEAD-FREE, 2µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL UNDERPLATE.
 - b - MANUFACTURING PROCESS COMPATIBILITY
 - THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.
 - c - LABELING:
 - MEETS PACKAGING SPECS AS PER GS-14-920
 - d - LEGAL STATEMENT: SEE GS-47-0004

91625-6XXLF	2 µm GOLD	Sn
91625-4XXLF	2 µm Sn	Sn
91625-3XXLF	0.76 µm GOLD	Sn
PLATING CODE	CONTACT AREA	SOLDER TAIL
	PLATING THICKNESS OVER 1.27µm Ni	

mat'l. code SEE NOTES	surface ISO 1302	tolerance ISO 406 ISO 1001	projection mm	product family DX VCC DR
lfr ecn no dr date	tolerances unless otherwise specified	angles linear	scale 10:1	file TOP ENTRY SELECT.LOADED
K F07-0154 DLE 07.03.15				dwg no 91625
L F07-0271 LMU 07.12.06				sheet 1 of 2 size A2
M F11-0314 LMU 11.10.28				type CUSTOMER Drawing
N B-19124 LMU 14.10.21 dr P.NIZZI 96.04.24				
P B-21076 LMU 15.06.05 engr J.M.PHAMVAN 96.04.24				
R F-47158 DDE 23.02.01 chr P.NIZZI 96.04.24				
sheet index	revision sheet	R P		
	1 2			

